

Press release

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AT&S offers new outstanding Embedded Power Electronics solutions

- AT&S achieved first disruptive technology for power electronics solutions for automotive and industrial applications
- First reference designs show significant miniaturisation up to 50% for power modules
- Power applications in different power classes in the range from 50 W to 50 kW
- 50 W power applications are ready for industrialisation

[AT&S](#) is the leading provider for Embedded Component Packaging Solutions. Its patented ECP® technology enables further miniaturisation while improving performance. Due to its constant technology development and strong partnerships, AT&S now achieved outstanding results in the field of power electronics. This solution provides a significant increase in efficiency and performance for Industrial and Automotive Applications.

Together with the EmPower consortium consisting of important industrial players and scientific partners, the development of embedded power packages is now ready for industrialisation. After 18 months of project work, first impressive results have become visible especially by benchmarking with existing packaging solutions: Reference designs have already been produced and show miniaturisation levels up to 50% for power modules. With the new embedding packaging concepts, an efficiency increase through reduction of power losses and reduced thermal resistances has been demonstrated. New plating equipment for wafer level plating has been developed in order to realise double sided copper plated power dies. This enables a new supply chain for embedded power devices and new packaging solutions.

Based on this positive development leading companies from the Automotive, Industrial & Semiconductor industrial sectors are now on the way to industrialise these new package solutions. Power applications (e.g DC/AC, renewable power solutions) classified in different power ranges from 50 W to 50 kW are targets on the industrialisation plan.

[Andreas Gerstenmayer](#), CEO AT&S: “The increasing demand in power electronics confirms our strategy to focus on innovative and efficient methods to optimise the use of energy. Based on the results achieved, AT&S is now able to offer customers and potential customers in the Automotive, Industrial as well as in the semiconductor industry our innovative embedded power electronic packaging solutions.”

The EmPower consortium consists of the following members:

- AT&S – Austria,
- Continental – Germany
- STMicroelectronics – France/Italy
- TU Wien – Austria
- TU Berlin – Germany
- Atotech – Germany
- Ilfa – Germany
- Fundico – Belgium



AT & S Austria Technologie & Systemtechnik
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About AT&S

AT&S is the European market leader and one of the leading manufacturers of high-value printed circuit boards. For more [information](#)

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